

DTA143ZE

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DTA143ZE

150mW Bias Resistor PNP Transistor

Features

- Built-in bias resistors enable the configuration of an inverter circuit without connecting external input resistors (see equivalent circuit).
- The bias resistors consist of thin-film resistors with complete isolation to allow positive biasing of the input. They also have the advantage of almost completely eliminating parasitic effects.
- Only the on/off conditions need to be set for operation, making the device design easy.
- We declare that the material of product compliance with RoHS requirements.
- Suffix "-H" indicates Halogen free parts, ex. DTA143ZE-H.

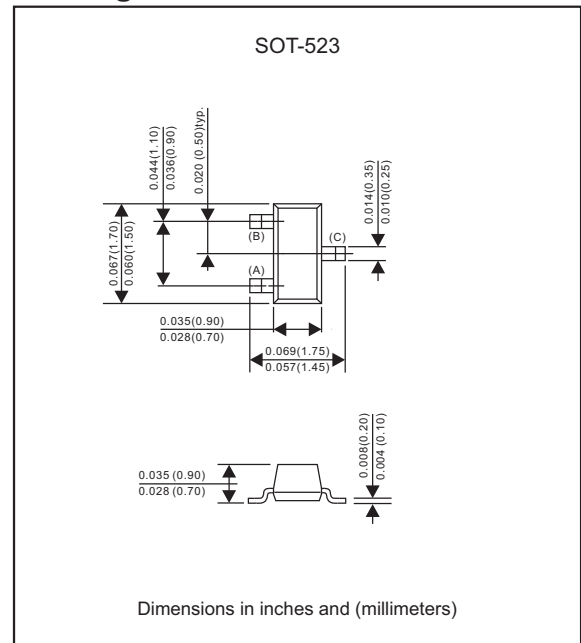
Applications

- Inverter, Interface, Driver

Mechanical data

- Epoxy:UL94-V0 rated flame retardant
- Case : Molded plastic, SOT-523
- Terminals : Solder plated, solderable per MIL-STD-750, Method 2026
- Mounting Position : Any
- Weight : Approximated 0.003 gram

Package outline



Maximum ratings (AT $T_A=25^{\circ}\text{C}$ unless otherwise noted)

PARAMETER	Symbol	Limits	UNIT
Collector Emitter Voltage	V_{CE}	-50	V
Input Voltage	V_{IN}	-30 to +5	V
Collector Current	I_C	100	mA
Power Dissipation	P_D	150	mW
Operating junction temperature range	T_J	-55 to +150	$^{\circ}\text{C}$
Storage temperature range	T_{STG}	-55 to +150	$^{\circ}\text{C}$

Electrical characteristics (AT $T_A=25^{\circ}\text{C}$ unless otherwise noted)

PARAMETER	CONDITIONS	Symbol	MIN.	TYP.	MAX.	UNIT
DC Current Gain	$V_{CE} = -5V, I_C = -10mA$	h_{FE}	80			-
Collector Base Cutoff Current	$V_{CC} = -50V, V_I = 0$	I_{CBO}			-0.5	μA
Emitter Base Cutoff Current	$V_{EB} = -5V$	I_{EBO}			-1.8	mA
Collector Emitter Saturation Voltage	$I_C = -5mA, I_B = -0.25mA,$	$V_{CE(sat)}$			-0.3	V
Input off Voltage	$V_{CE} = -5.0V, I_O = -100\mu A$	$V_{I(off)}$			-0.5	V
Input on Voltage	$V_{CE} = -0.3V, I_O = -5mA$	$V_{I(on)}$	-1.3			V
Transition Frequency	$V_{CE} = -10V, I_E = -5mA, f = 100MHz$	f_T		250		MHz
Input Resistance		R_1	3.29	4.7	6.11	K Ω
Resistance Ratio		R_2/R_1	8	10	12	-

* Characteristics of built-in transistor

Rating and characteristic curves (DTA143ZE)

Fig.1 Input voltage vs. output current (ON characteristics)

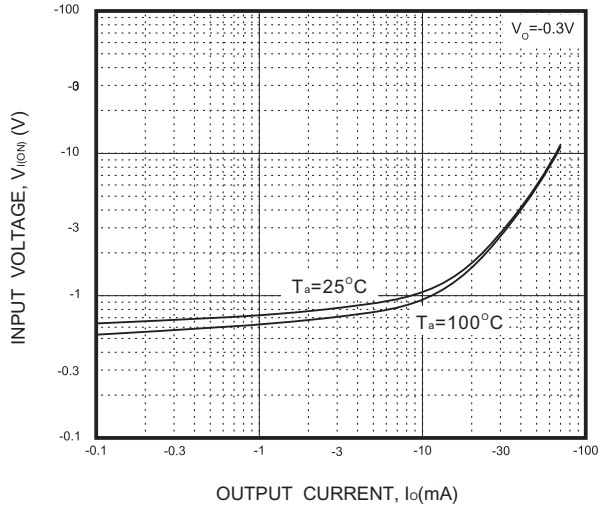


Fig.2 Output current vs. Input voltage (OFF characteristics)

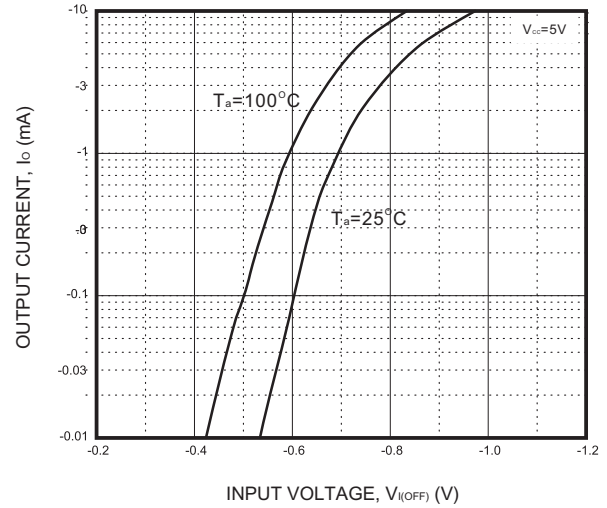


Fig.3 DC current gain vs. output current

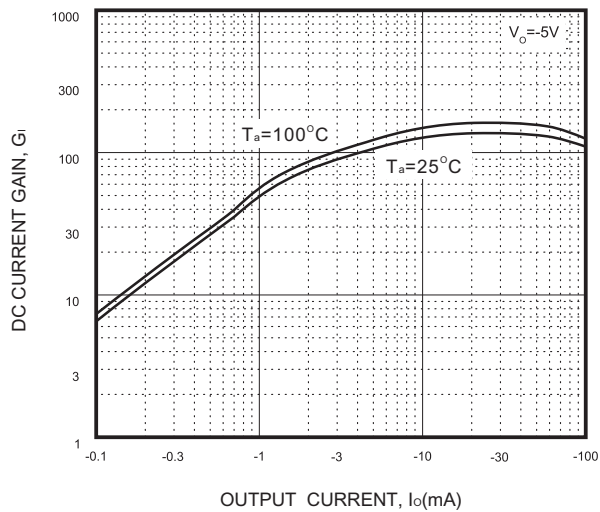
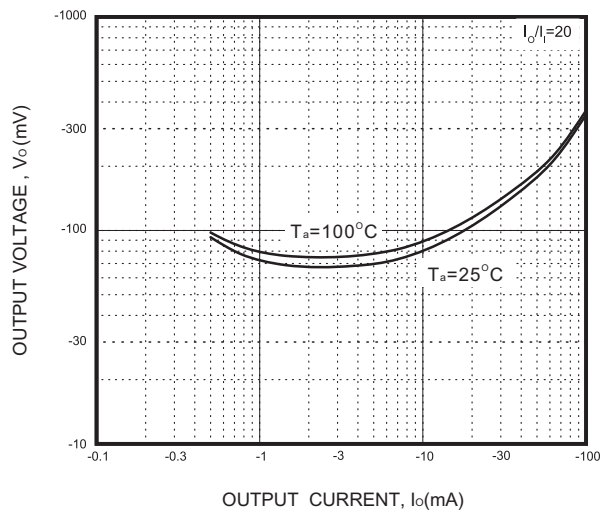
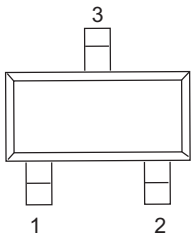
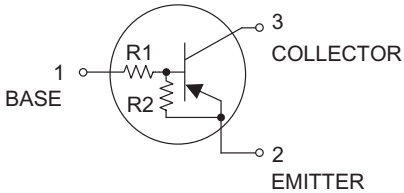


Fig.4 Output voltage vs. output current



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Pinning information

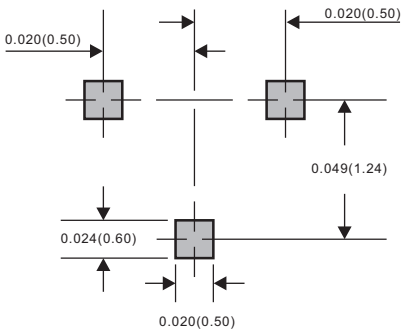
Pin	Simplified outline	Symbol
Pin1 BASE Pin2 EMITTER Pin3 COLLECTOR		

Marking and resistor values

Type number	Marking Code
DTA143ZE	E13

Suggested solder pad layout

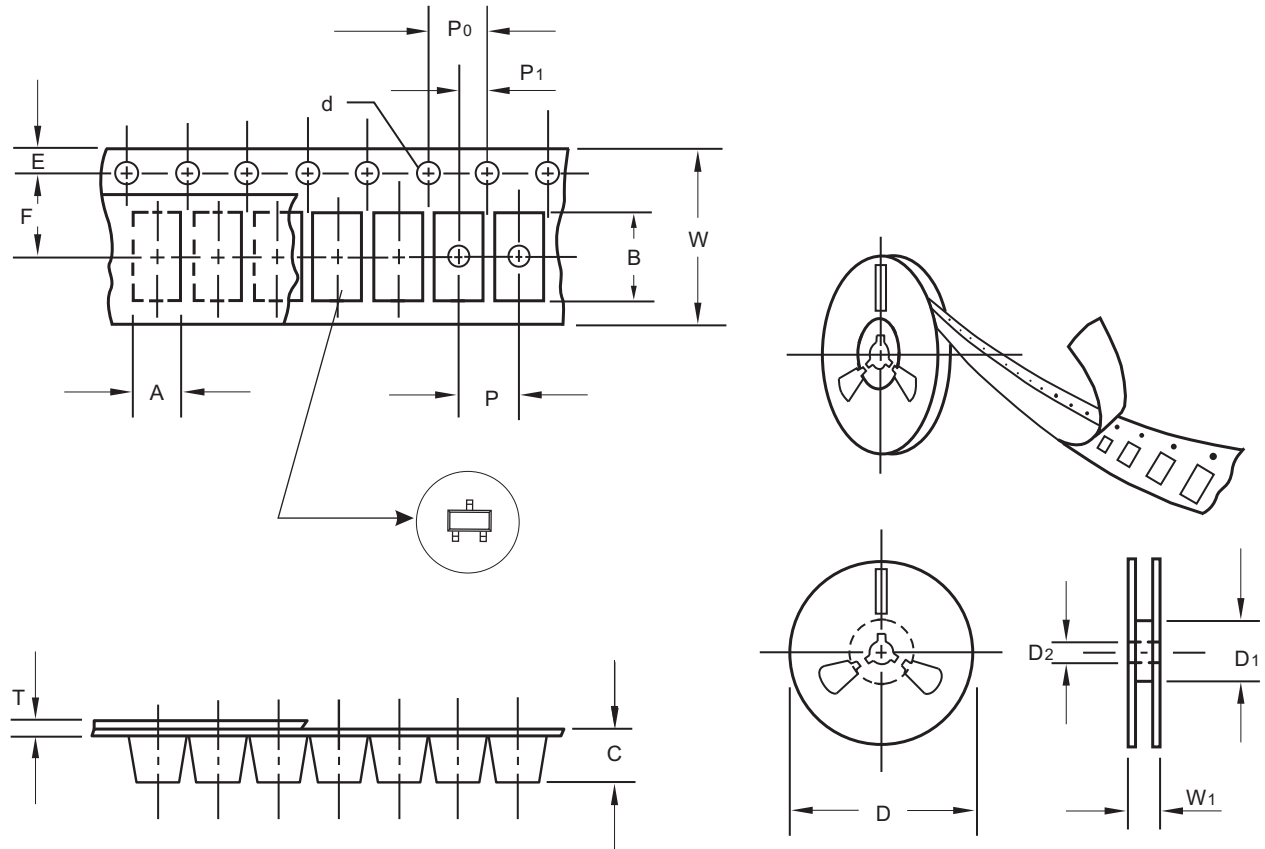
SOT-523



Dimensions in inches and (millimeters)

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Packing information



unit:mm

Item	Symbol	Tolerance	SOT-523
Carrier width	A	0.1	1.85
Carrier length	B	0.1	1.85
Carrier depth	C	0.1	0.875
Sprocket hole	d	0.1	1.50
13" Reel outside diameter	D	2.0	-
13" Reel inner diameter	D1	min	-
7" Reel outside diameter	D	2.0	178.00
7" Reel inner diameter	D1	min	54.40
Feed hole diameter	D2	0.5	13.00
Sprocket hole position	E	0.1	1.75
Punch hole position	F	0.1	3.50
Punch hole pitch	P	0.1	4.00
Sprocket hole pitch	P0	0.1	4.00
Embossment center	P1	0.1	2.00
Overall tape thickness	T	0.1	0.23
Tape width	W	0.3	8.00
Reel width	W1	1.0	11.4

Note: Devices are packed in accordance with EIA standard RS-481-A and specifications listed above.

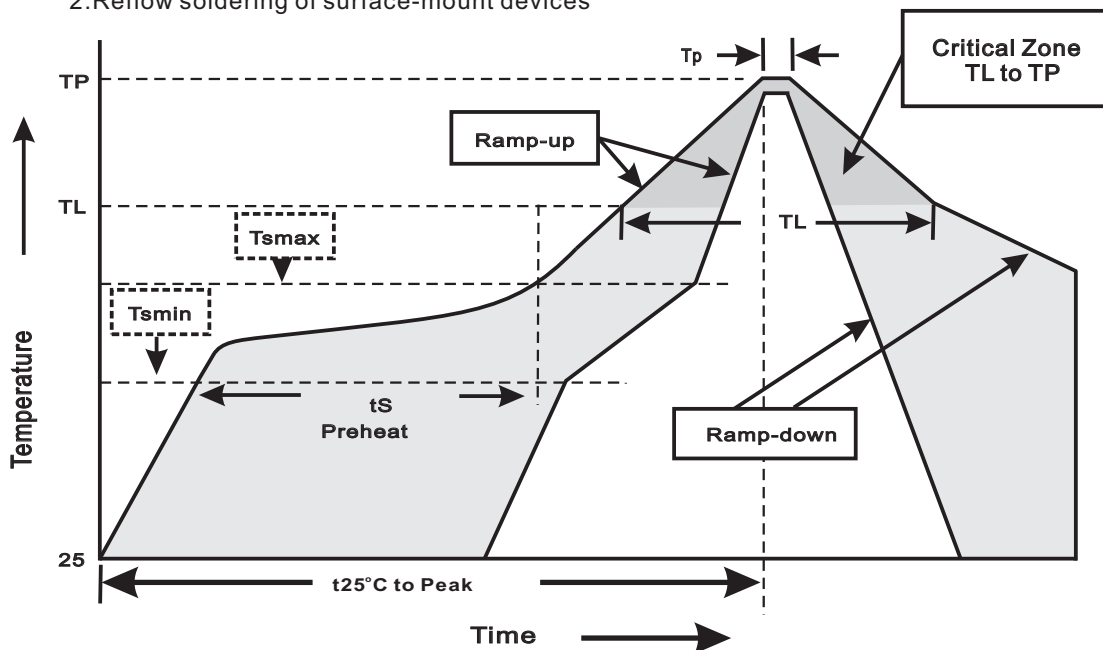
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Reel packing

PACKAGE	REEL SIZE	REEL (pcs)	COMPONENT SPACING (m/m)	BOX (pcs)	INNER BOX (m/m)	REEL DIA, (m/m)	CARTON SIZE (m/m)	CARTON (pcs)	APPROX. GROSS WEIGHT (kg)
SOT-523	7"	3,000	4.0	30,000	183*123*183	178	382*257*387	240,000	11.6

Suggested thermal profiles for soldering processes

- 1.Storage environment: Temperature=5°C~40°C Humidity=55%±25%
- 2.Reflow soldering of surface-mount devices



3.Reflow soldering

Profile Feature	Soldering Condition
Average ramp-up rate(T _L to T _P)	<3°C/sec
Preheat -Temperature Min(T _{smmin}) -Temperature Max(T _{smmax}) -Time(min to max)(t _s)	150°C 200°C 60~120sec
T _{smmax} to T _L -Ramp-upRate	<3°C/sec
Time maintained above: -Temperature(T _L) -Time(t _L)	217°C 60~260sec
Peak Temperature(T _P)	255°C-0/+5°C
Time within 5°C of actual Peak Temperature(t _P)	10~30sec
Ramp-down Rate	<6°C/sec
Time 25°C to Peak Temperature	<6minutes